

SOT1519-1

LFBGA356; plastic, low profile fine-pitch ball grid array; 356 bumps; 0.8 mm pitch; 17 mm x 17 mm x 1.54 mm body

21 February 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA356
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-01-2016
Manufacturer package code	98ASA00478D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
seated height	-	1.54	1.7	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	356	-	



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2 Package outline

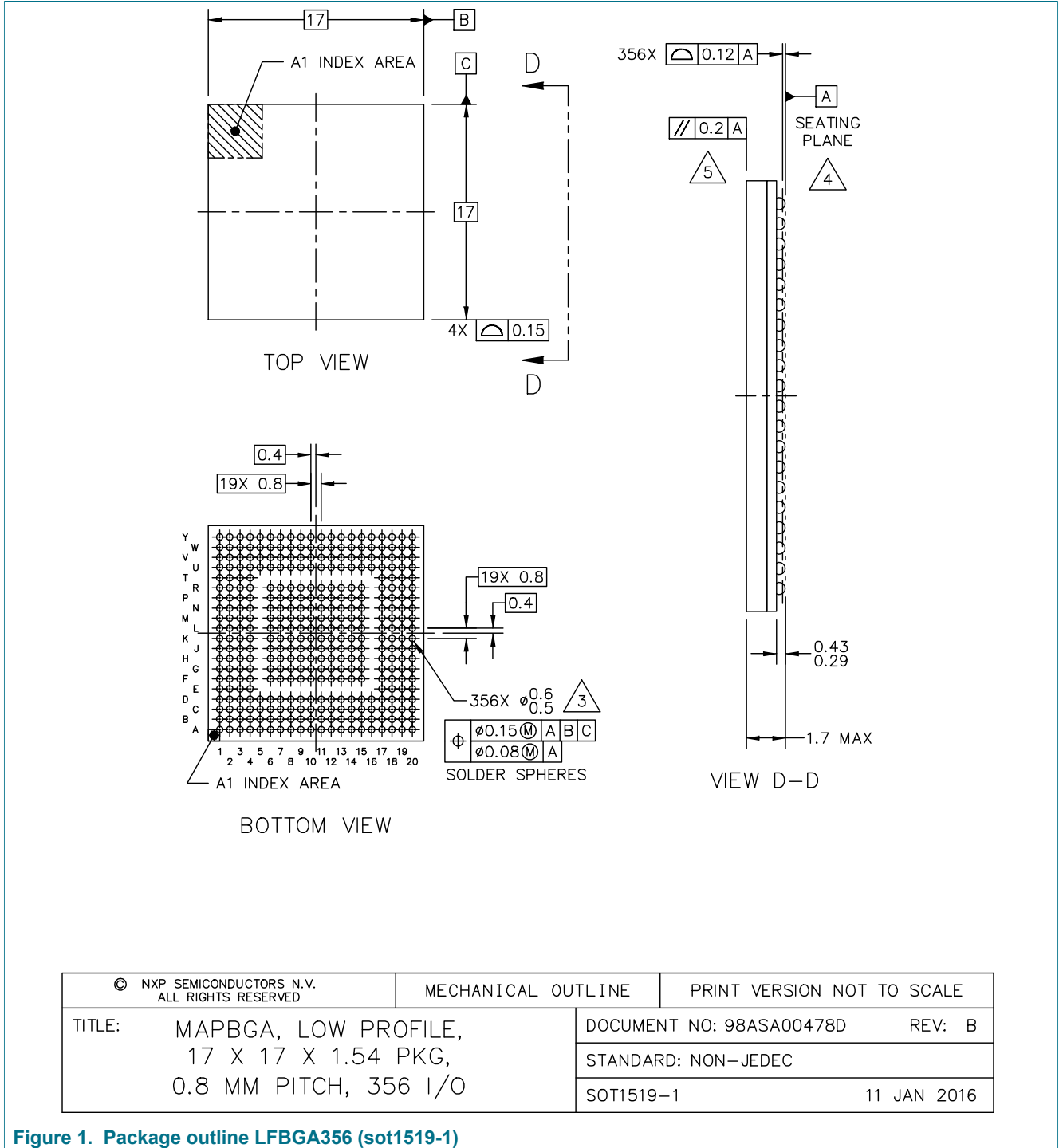


Figure 1. Package outline LFBGA356 (sot1519-1)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: MAPBGA, LOW PROFILE, 17 X 17 X 1.54 PKG, 0.8 MM PITCH, 356 I/O	DOCUMENT NO: 98ASA00478D	REV: B	
	STANDARD: NON-JEDEC		
	SOT1519-1	11 JAN 2016	

Figure 2. Package outline note LFBGA356 (sot1519-1)

3 Legal information

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